



# Material Composition Declaration

## EPC2020

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/4/2016
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	25.0 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	21.8755	87.38	89.71	873787
	Silicon oxide	7631-86-9	0.0847	0.34		3382
	Silicon nitride	12033-89-5	0.0275	0.11		1099
	Gallium nitride	25617-97-4	0.1031	0.41		4118
	Aluminum	7429-90-5	0.1695	0.68		6771
	Aluminum nitride	24304-00-5	0.0248	0.10		992
	Titanium	7440-32-6	0.0044	0.02		177
	Titanium nitride	25583-20-4	0.0158	0.06		630
	Copper	7440-50-8	0.0056	0.02		225
	Tungsten	7440-33-7	0.0069	0.03		275
	Polyimide		0.1407	0.56		5622
Under Bump Metal	Titanium	7440-32-6	0.0037	0.01	1.23	146
	Nickel	7440-02-0	0.1086	0.43		4337
	Vanadium	7440-62-2	0.0000	0.00		0
	Copper	7440-50-8	0.1966	0.79		7851
Solder Bump	Tin	7440-31-5	2.2112	8.83	9.06	88323
	Silver	7440-22-4	0.0567	0.23		2265
	Copper	7440-50-8	0.0000	0.00		0
Sum in total:			25.0	100.00	100	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.